

REMARKS/ARGUMENTS

Initially, Applicants would like to express their appreciation to the Examiner for the detailed Official Action provided, for the acknowledgment of Applicants' Information Disclosure Statements by return of the Form PTO-1449s, and for the acknowledgment of Applicants' Claim for Priority and receipt of the certified copy of the priority document in the Official Action, and for acknowledgement that the drawings are acceptable.

Upon entry of the above amendments, claims 7 and 11 will have been amended, and claims 13 and 14 will have been added. Claims 1-14 are currently pending, with claims 1-6 being withdrawn from consideration in a previous Official Action. Applicants respectfully request reconsideration of the outstanding rejections, and allowance of all the claims pending in the present application.

Initially, we note that the Examiner has pointed out that the preamble of claim 11 (which depends from claim 7) recites an "optical disc manufacturing apparatus," whereas the preamble of claim 7 recites an "optical disc manufacturing method." Therefore, we have amended the preamble of claim 11 to recite an "optical disc manufacturing method" solely to conform to the language of claim 7, from which claim 11 depends.

In the Official Action, the Examiner has rejected claims 7, 8 and 10-12 under 35 U.S.C. § 102(b) as being anticipated by YATAKE (U.S. Patent No. 5,197,060).

Although Applicants do not necessarily agree with the Examiner's rejection of the claims on these grounds, Applicants nevertheless have amended

independent claim 7 to more clearly obviate the above-noted grounds of rejection solely in order to expedite prosecution of the present application. In this regard, Applicant notes that YATAKE fails to teach or suggest the combination of elements as recited in amended claim 1. In particular, claim 1 sets forth a laminated optical disc manufacturing method including, inter alia, locally irradiating the adhesive layer such that the adhesive layer is partially cured thereby provisionally bonding the first and second substrates.

Applicants submit that YATAKE lacks any disclosure of at least the above-noted combination of elements.

In this regard, we note the method disclosed in YATAKE is very different methodically from the method of the present claimed invention. More particularly, YATAKE discloses irradiating (*via* 27 and 28) the entire disk in order to cure UV-curing components of the adhesive in the inner and outer circumference parts of the substrates (see, FIG. 2(e)). Therefore, YATAKE does not disclose at least locally irradiating the adhesive layer such that the adhesive layer is partially cured thereby provisionally bonding the first and second substrates.

Absent a disclosure in a single reference of each and every element recited in a claim, a *prima facie* case of anticipation cannot be made under 35 U.S.C. § 102. Since the applied reference fails to disclose each and every element recited in independent claim 7, as well as claims 8-14 depending therefrom, these claims are not anticipated thereby. Further, all pending dependent claims recite additional features that further define the present

invention over the prior art. Accordingly, the Examiner is respectfully requested to withdraw the rejection under 35 U.S.C. § 102 and allow all pending claims in the present application.

In the Official Action, the Examiner has rejected claim 9 under 35 U.S.C. § 103(a) as being unpatentable over YATAKE in view of AKAGAWA (U.S. Patent No. 5,000,651).

Applicants respectfully traverse the above noted rejections of claim 9 under 35 U.S.C. § 103(a).

Applicants submit that dependent claim 9 is patentable due to its dependency from claim 7 for at least the reasons noted above. In this regard, Applicants note that the Examiner has provided no explanation or motivation for correcting the above-noted deficiencies in the teachings of YATAKE. Applicants further submit that AKAGAWA does not provide any teachings which could reasonably be characterized as curing the above-noted deficiencies in the teachings of YATAKE. In this regard, Applicants submit that AKAGAWA does not disclose at least locally irradiating the adhesive layer such that the adhesive layer is partially cured thereby provisionally bonding the first and second substrates. Accordingly, the Examiner is respectfully requested to withdraw the rejection under 35 U.S.C. § 103 and allow all pending claims in the present application.

Applicants further submit that new dependent claims 13 and 14 recite additional features of non-limiting embodiments of the present claimed invention, and no new matter is believed to have been added by the present amendment.

In this regard, support for the features recited in the aforementioned claims can be found at least in the last paragraph beginning on page 43 of the present disclosure and on page 27, lines 9-13, of the present disclosure.

In view of the remarks herein-contained, Applicants submit that independent claim 7 is in condition for allowance. With regard to dependent claims 8-14, Applicants assert that they are allowable on their own merit, as well as because of their dependencies from independent claim 7, which Applicants have shown to be allowable.

Thus, it is respectfully submitted that all of the claims in the present application are clearly patentable over the references cited by the Examiner, either alone or in combination, and an indication to such effect is respectfully requested, in due course.

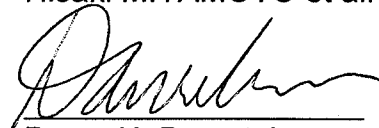
### SUMMARY

Applicants submit that the present application is in condition for allowance, and respectfully request an indication to that effect. Applicants have argued the allowability of the claims and pointed out deficiencies of the applied reference. Accordingly, reconsideration of the outstanding Official Action and allowance of the present application and all the claims therein are respectfully requested and is now believed to be appropriate.

Applicants note that this amendment is being made solely to advance prosecution of the application to allowance and should not be considered as surrendering equivalents of the territory between the claims prior to the present amendment and the amended claims. Further, no acquiescence as to the propriety of the Examiner's rejection is made by the present amendment. All other amendments to the claims which have been made in this amendment, and which have not been specifically noted to overcome a rejection based upon the prior art, should be considered to have been made for a purpose unrelated to patentability, and no estoppel should be deemed to attach thereto.

Should the Examiner have any questions, the Examiner is invited to contact the undersigned at the below-listed telephone number.

Respectfully submitted,  
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